**PATENT ASSIGNMENT**

Electronic Version v1.1  
Stylesheet Version v1.1

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<tr>
<th>SUBMISSION TYPE:</th>
<th>NEW ASSIGNMENT</th>
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<th>ASSIGNMENT</th>
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### CONVEYING PARTY DATA

<table>
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<tr>
<th>Name</th>
<th>Execution Date</th>
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</thead>
<tbody>
<tr>
<td>Boung Ju Lee</td>
<td>05/15/2006</td>
</tr>
<tr>
<td>Heon Jong Shin</td>
<td>05/15/2006</td>
</tr>
<tr>
<td>Hee Sung Kang</td>
<td>05/15/2006</td>
</tr>
</tbody>
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### RECEIVING PARTY DATA

<table>
<thead>
<tr>
<th>Name:</th>
<th>Samsung Electronics Co., Ltd.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Street Address:</td>
<td>416 Maetan-dong</td>
</tr>
<tr>
<td>Internal Address:</td>
<td>Yeongtong-gu, Suwon-si</td>
</tr>
<tr>
<td>City:</td>
<td>Gyeonggi-do</td>
</tr>
<tr>
<td>State/Country:</td>
<td>KOREA, REPUBLIC OF</td>
</tr>
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### PROPERTY NUMBERS Total: 1

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<tr>
<td>Application Number</td>
<td>11421202</td>
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### CORRESPONDENCE DATA

Fax Number: (919)854-1401  
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 919-854-1400  
Email: criggs@myersbigel.com  
Correspondent Name: Candi L. Riggs / MBSS  
Address Line 1: 4140 Parklake Avenue  
Address Line 2: Suite 600  
Address Line 4: Raleigh, NORTH CAROLINA 27612

### ATTORNEY DOCKET NUMBER: 5649-1784

### NAME OF SUBMITTER: Grant J. Scott

Total Attachments: 4  
source=Assignment#page1.tif
ASSIGNMENT


WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in METHODS OF FORMING DUAL-DAMASCENE METAL WIRING PATTERNS FOR INTEGRATED CIRCUIT DEVICES AND WIRING PATTERNS FORMED THEREBY for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. 11/421,202, filed 5/31/2006) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, SAMSUNG ELECTRONICS CO., LTD., a Korean corporation having a principal place of business at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International
ASSIGNMENT – CONTINUED

Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 15th day of May, 2006.

______________________________
Boung Ju Lee (SEAL)

Boung Ju Lee

Witnessed by:

________________________________________

Date:____________________________________
ASSIGNMENT – CONTINUED

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 15th day
of May, 2006.

________________________________________
Heon Jong Shin (SEAL)
Heon Jong Shin

Witnessed by:

________________________________________

Date:_____________________________________
IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 15th day of May, 2006.

[Signature]
Hee Sung Kang (SEAL)

Witnessed by:

______________________________

Date: _________________________